

Title (en)
COUPLING DEVICE, ASSEMBLY HAVING A COUPLING DEVICE, AND METHOD FOR PRODUCING AN ASSEMBLY HAVING A COUPLING DEVICE

Title (de)
KOPPELVORRICHTUNG, ANORDNUNG MIT EINER KOPPELVORRICHTUNG, VERFAHREN ZUR HERSTELLUNG EINER ANORDNUNG MIT EINER KOPPELVORRICHTUNG

Title (fr)
DISPOSITIF DE COUPLAGE, SYSTÈME COMPORTANT UN DISPOSITIF DE COUPLAGE, PROCÉDÉ DE FABRICATION D'UN SYSTÈME COMPORTANT UN DISPOSITIF DE COUPLAGE

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Application
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Priority
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Abstract (en)
[origin: WO2011047955A1] The invention relates to a method for a coupling device (1) for connecting an electrical/electronic component (16), in particular a sensor (17), having a substrate, in particular a circuit board, wherein the coupling device (1) comprises at least one electrical connection (25) for electrical contacting and at least one damper element (12) for movement uncoupling, wherein the electrical connection is formed by a lead frame (3) and the lead frame (3) is overmolded in regions by a damping mass (11) as a damper element (12). The invention furthermore relates to an assembly having a coupling device and a method for producing said type of assembly.

IPC 8 full level
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CPC (source: EP KR US)
B29C 45/14 (2013.01 - KR); **H05K 1/0271** (2013.01 - EP KR US); **H05K 3/20** (2013.01 - KR); **H05K 3/4084** (2013.01 - EP US); **B29C 45/14** (2013.01 - EP US); **H01L 2924/0002** (2013.01 - EP US); **H05K 3/202** (2013.01 - EP US); **H05K 2201/0133** (2013.01 - EP US); **H05K 2201/09118** (2013.01 - EP US); **H05K 2201/10151** (2013.01 - EP US); **H05K 2201/10378** (2013.01 - EP US); **Y10T 29/49146** (2015.01 - EP US)

C-Set (source: EP US)
H01L 2924/0002 + H01L 2924/00

Citation (search report)
See references of WO 2011047955A1

Citation (examination)
• US 2008157806 A1 20080703 - LEE SOO HO [KR]
• US 5394751 A 19950307 - ISHIBASHI KIYOSHI [JP]

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DOCDB simple family (publication)
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